

# Hiner-pack® FHWS Canister 200 mm

*Protects wafers from contamination during secure transport and storage*

Engineered for secure transport and storage of wafer-attached flex, dicing, or film frame in semiconductor packaging, this shipper delivers critical protection and automation compatibility. Its precision-molded slots immobilize frames, its perimeter support rings and inner contours cradle the metal or plastic frame rather than the wafer surface, preventing wafer slippage and micro-crack damage during handling. Lock catch secure system and inner side impact-resistant space design provide effective protection during wafer transportation. Constructed from anti-static PP, dust-free cleaning and packaging after completion of production, suitable for a 100-class purification workshop, ensures particle-free storage, which is critical in maintaining the integrity of sensitive wafers throughout the shipping process. Flex Frame Wafer Shippers are the ideal solution for semiconductor manufacturers seeking reliable and efficient transportation of multiple wafers mounted on dicing, flex, or film frames.



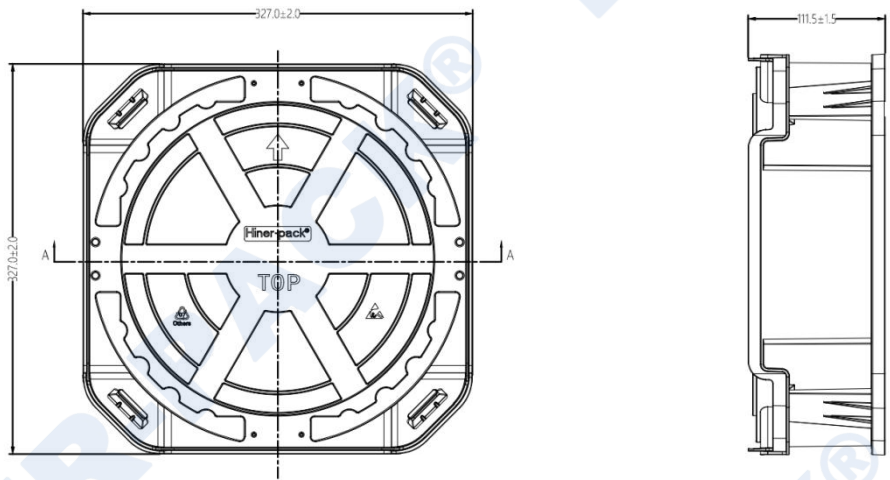
## SPECIFICATIONS

- 327 mm L × 327 mm W × 111.5 mm H (12.87" × 12.87" × 4.39")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (4)

## FEATURES & BENEFITS

- Secures wafers already mounted on flex, dicing, or film frame
- ESD-safe and made from low-particle/ionic/outgassing material
- Stackable design protects wafers from shock and edge damage
- Conforms to the automatic interface of process equipment
- Reusable for cost-efficient shipping

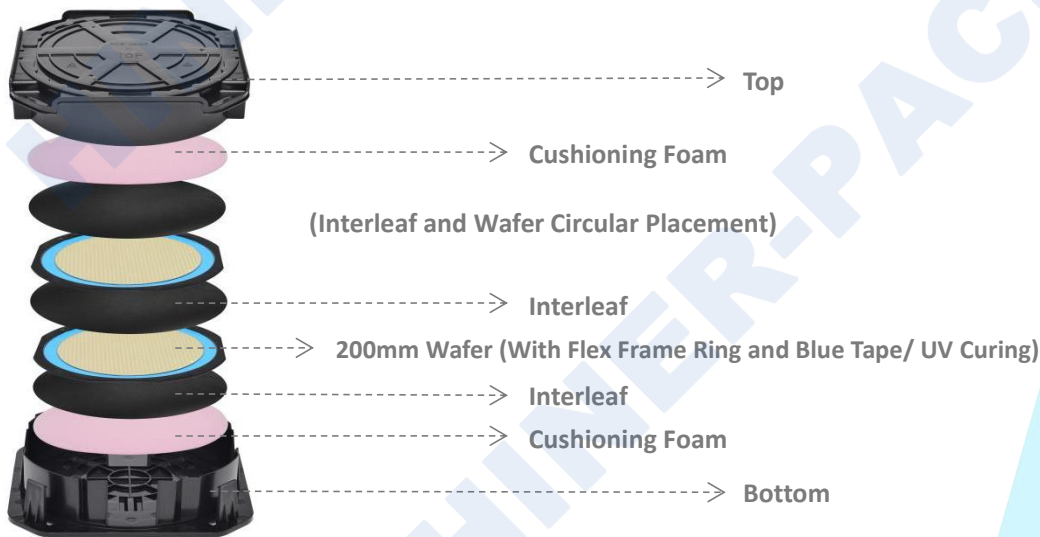
DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
FHWS-8/25	Bottom+Cushion+Interleaf+Frame+Top	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

## TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183-1 (23°C)	1.0 g/cm <sup>3</sup>
Melt Index (350°C/5kg)	ASTM D-1238	15.0 g/10min
Shrinkage Percentage	ISO 2577	1.2~1.6 %
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Strength (Fracture)	ISO 178 (2mm/min)	27 MPa
Flexural Modulus	ISO 178 (2mm/min)	1150 MPa
LZOD Notch Impact Strength (3.2mm)	ISO 180 (23°C)	30 kJ/m <sup>2</sup>
Surface Resistivity	ASTM D-257	1.0×10 <sup>4</sup> ~1.0×10 <sup>9</sup> Ω/sq
Flame Retardant Rating	UL 94	HB Class

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

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